















UJ3D1210TS

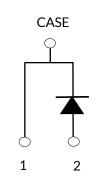


CASE



1

2



Part Number	Package	Marking
UJ3D1210TS	TO-220-2L	UJ3D1210TS











10A -1200V SiC Schottky Diode

Rev. C, February 2020

Description

UnitedSiC offers the 3rd generation of high performance SiC Merged-PiN-Schottky (MPS) diodes. With zero reverse recovery charge and 175°C maximum junction temperature, these diodes are ideally suited for high frequency and high efficiency power systems with minimum cooling requirements.

Features

- Maximum operating temperature of 175°C
- Easy paralleling
- Extremely fast switching not dependent on temperature
- No reverse or forward recovery
- Enhanced surge current capability, MPS structure
- Excellent thermal performance, Ag sintered
- 100% UIS tested
- AEC-Q101 qualified

Typical applications

- Power converters
- Industrial motor drives
- Switch mode power supplies
- Power factor correction modules













Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units	
DC blocking voltage	V _R		1200	V	
Repetitive peak reverse voltage, T _J =25°C	V_{RRM}		1200	V	
Surge peak reverse voltage	V_{RSM}		1200	V	
Maximum DC forward current	I _F	T _C = 157°C	10	Α	
Non-repetitive forward surge current	1	$T_C = 25$ °C, $t_p = 10$ ms	120	А	
sine halfwave	I _{FSM}	$T_C = 110^{\circ}C, t_p = 10 \text{ms}$	110		
Repetitive forward surge current		$T_C = 25$ °C, $t_p = 10$ ms	54.2	Α	
sine halfwave, D=0.1	I _{FRM}	$T_C = 110^{\circ}C, t_p = 10 \text{ms}$	32.3		
Non-repetitive peak forward current	I _{F,max}	$T_C = 25$ °C, $t_p = 10 \mu s$	720	А	
		$T_C = 110^{\circ}C, t_p = 10\mu s$	720		
i ² t value	∫i²dt -	$T_C = 25$ °C, $t_p = 10$ ms	72	A 2 -	
		$T_C = 110^{\circ}C, t_p = 10 \text{ms}$	60	A^2s	
Power dissipation	P _{tot} -	T _C = 25°C	220.6	14/	
		T _C = 157°C	26.5	W	
Maximum junction temperature	$T_{J,max}$		175	°C	
Operating and storage temperature	T _J , T _{STG}		-55 to 175	°C	
Soldering temperatures, wavesoldering only allowed at leads	T_{sold}	1.6mm from case for 10s	260	°C	

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value			Units
			Min	Тур	Max	Offits
Thermal resistance, junction-to-case	$R_{\theta IC}$			0.52	0.68	°C/W

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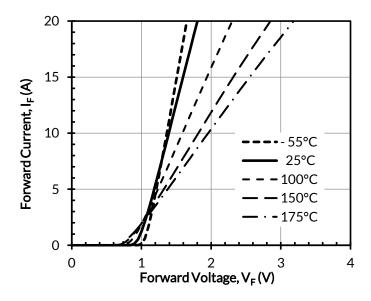


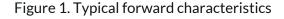
Electrical Characteristics (T_J = +25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Value			Units	
			Min	Тур	Max	Units	
Forward voltage	V _F	I _F = 10A, T _J =25°C	-	1.4	1.6		
		I _F = 10A, T _J = 150°C	-	1.85	2.3	V	
		I _F = 10A, T _J = 175°C	-	2	2.6		
Reverse current	I _R	V _R =1200V, T _J =25°C	-	10	110	μΑ	
		V _R =1200V, T _J =175°C	-	450			
Total capacitive charge (1)	Q _C	V _R =800V		51		nC	
Total capacitance	С	$V_R=1V, f=1MHz$		510			
		V _R =400V, f = 1MHz		48		pF	
		V _R =800V, f = 1MHz		41			
Capacitance stored energy	E _C	V _R =800V		15		μЈ	

(1) Q_c is independent on T_J , di_F/dt , and I_F as shown in the application note USCi_AN0011.

Typical Performance Diagrams





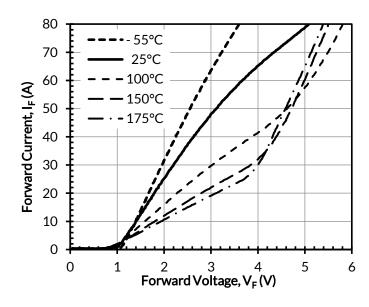


Figure 2. Typical forward characteristics in surge current



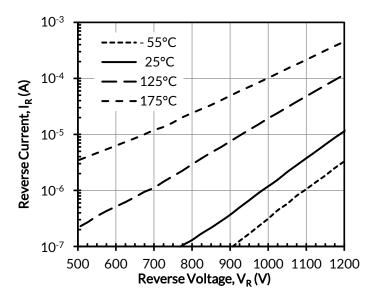








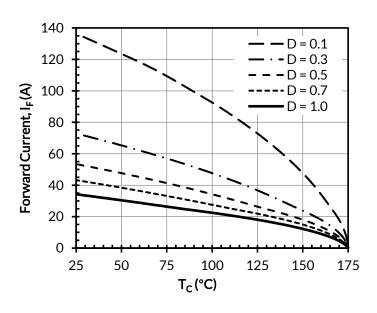




250 200 200 4 uointeidss 150 25 50 75 100 125 150 175 T_c(°C)

Figure 3. Typical reverse characteristics

Figure 4. Power dissipation



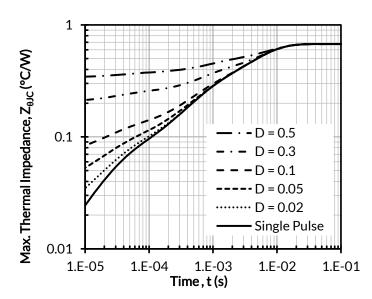


Figure 5. Diode forward current

Figure 6. Maximum transient thermal impedance



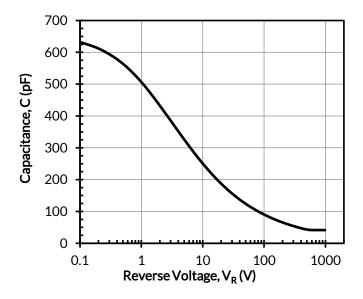












 $Q_{\rm c}$ (nC) $Q_{C} = \int_{0}^{V_{R}} C(V) dV$ Reverse Voltage, $V_R(V)$

Figure 7. Capacitance vs. reverse voltage at 1MHz

Figure 8. Typical capacitive charge vs. reverse voltage

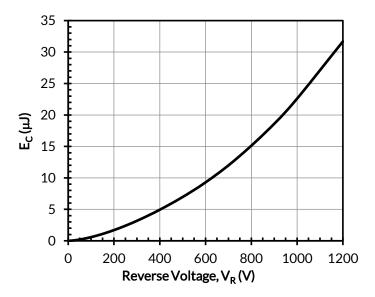


Figure 9. Typical capacitance stored energy vs. reverse voltage













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